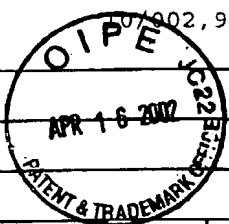


FORM PTO-1449		Atty. Docket Number: H60-104 US		Serial Number: 10/202,996	
LIST OF PRIOR ART CITED BY APPLICANT		Applicant: J. Ramm			
		Filing Date: 10/25/01		Group:	



U.S. PATENT DOCUMENTS													
EI*		Document Number							Date	Name	Class	Sub-class	Filing Date
FH	AA	4	0	5	8	4	3	0	11/15/77	Suntola et al.	156	611	11/25/75
↑	AB	4	3	8	9	9	7	3	06/28/83	Suntola et al.	118	275	12/11/81
	AC	4	4	1	3	0	2	2	11/01/83	Suntola et al.	427	255.2	06/21/79
	AD	5	0	7	1	6	7	0	12/10/91	Kelly	427	38	06/11/90
	AE	5	9	1	6	3	6	5	06/29/99	Sherman	117	92	08/16/96
↓	AF	5	9	7	2	4	3	0	10/26/99	DiMeo, Jr. et al.	427	255.3	11/26/97
FH	AG	6	0	1	5	5	9	0	01/18/00	Suntola et al.	427	255.2	11/28/95
	AH												
	AI												
	AJ												
	AK												

FOREIGN PATENT DOCUMENTS														
		Document Number							Date	Country	Class	Sub-class	Translated	
													Y	N
	AL													
	AM													
	AN													
	AO													
	AP													

Other Prior Art (incl. Author, Title, Date, Pertinent Pages, etc.)		
FH	AR	Hiramatsu, K, et al., "Formation of TiN films with low CI concentration by pulsed plasma chemical vapor deposition", <u>J. Vac. Sci. Technol.</u> A 14(3) May/Jun 1996, 1037-1040.
FH	AS	Rossnagel, S.M., "Plasma-enhanced atomic layer deposition of Ta and Ti for interconnect diffusion barriers", <u>J. Vac. Sci. Technol.</u> B 18(4), Jul/Aug 2000, 2016-2020.
FH	AT	Swiss Search Report, dated July 27, 2001.

Examiner: <i>F. H. H. H.</i>	Date Considered: 1/14/04
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with 1 Draw line through citation if not in conformance and not considered. Include copy of this 1 next communication to applicant.